Contact Name  Title - Contact  Product-Env-Stewards  Product-Env-Stewards  Authorized Representative*  Product-Env-Stewards  Product	ASSOCIATION CONNECTING	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name*  Company unique ID  Unique ID Authority  Response Date*  2024-04-30  2024-04-30  Contact Name  Title - Contact*  Product Enviro Compliance  NA  Product-Env-Stewards  Product-Env-Stewar	752-21.1										als and Mfg	Information	on		
Semi	upplier Inform	ation								,					
Title - Contact Name Product Env-Stewards Product Enviro Compliance Product Env-Stewards Product Enviro Compliance Product Env-Stewards Product Enviro Compliance Product Env-Stewards Product Enviro Compliance Product Enviro Compliance Product Enviro Compliance NA Product Env-Stewards Product Enviro Compliance NA Product Enviro Compliance NA Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards Product Env-Stewards NA Nanufacturing Site Weight* UOM Unit Nanufacturing Proccess Information Proccess Information  Peak Process Body Temperature Nan Time at Peak Temperature Number of Reflow Cycles Natte Tin (Sn) - annealed Outline Stewards Nanufacturing Proccess Sody Temperature Number of Reflow Cycles Sody Seconds  Product Env-Stewards NA Nanufacturing Site Nanufacturing	Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
Product-Env-Stewards	onsemi											2024-04-30			
Authorized Representative*  Product-Env-Stewards Product Enviro Compliance Requester Item Number Requester Ite	Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product Envi-Stewards  Requester Item Number  Mfr Item Number  Mfr Item Number  Mfr Item Name  Effective Date  Version  Manufacturing Site  Weight*  UOM  Unit  Version  Manufacturing Site  Weight*  UOM  Unit  Version  Manufacturing Site  Weight*  Weight*  Wanufacturing Site  Weight*  Weight*  Wanufacturing Process Information  Ferminal Plating / Grid Array Material  Terminal Base Alloy  J-STD-020 MSL Rating  Matte Tin (Sn) - annealed  CU Alloy  1 260  C 30 seconds  Terminal Plating / Grid Array Material  NA  Product-Env-Stewards@onsemi.com  Manufacturing Site  Weight*  Weight*  UOM  Unit  Peach  Process Body Temperature  Max Time at Peak Temperature  Number of Reflow Cycles  Seconds  Terminal Plating / Grid Array Material  Number of Reflow Cycles  Seconds 3	Product-Env-Stewards			Product Enviro Compliance			]	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Authorized Representative*			Title - Representative			I	Phone - Representative*				Email - Representative*			
NVTFS5826NLTWG NFET U8FL 60V 20A 25MOHM 2024-04-30 MY1 29.38 mg Each  Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles and Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles  Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requeste	Requester Item Number Mfr Ite		m Number Mfr Item Name				Effective Date	Version	N	Manufacturing Site		eight*	UOM	Unit Type
Terminal Plating / Grid Array Material  Terminal Base Alloy  J-STD-020 MSL Rating  Peak Process Body Temperature  Max Time at Peak Temperature  Number of Reflow Cycles  260  Comments			NVTFS5826NLTWG NFET U8FL 60V 2		20A 25MOHM	I	2024-04-30	1-30 MY1		29.	38	mg	Each		
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 omments					A.11	CTD 020 MCI	Datin -	Davida Dava	D - d T		Mary Time at Peak	T	Nous	and Buffers Con-	1
Comments				·		Rating							er of Reflow Cyc	eles	
	•	n (Sn) - annealed	C	U Alloy	1			200		IC.	30	seconds	3		
vei 1 - maximum ume at peak temperature during soldering is 10-50 seconds		·	Ji	Ji :. 10 2	0										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier need is a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides											
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temper	erature type solders (i.e. lead based solder	alloys containing 85% by weight or more lead).									
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-6_									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	0.38	mg	Supplier	Zinc (Zn)	7440-66-6		0.0005	mg
			Supplier	Iron (Fe)	7439-89-6		0.0089	mg
			Supplier	Copper (Cu)	7440-50-8		0.3705	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0001	mg
Die	0.3	mg	Supplier	Silicon (Si)	7440-21-3		0.3	mg
Die Attach Solder	0.65	mg	Supplier	Silver (Ag)	7440-22-4		0.0162	mg
			A	Lead (Pb)	7439-92-1	7a	0.6012	mg
			Supplier	Tin (Sn)	7440-31-5		0.0325	mg
Lead Frame	12.41	mg	Supplier	Silver (Ag)	7440-22-4		0.0074	mg
			Supplier	Iron (Fe)	7439-89-6		0.0124	mg
			Supplier	Copper (Cu)	7440-50-8		12.3864	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0037	mg
Mold Compound-Black	15.0	mg		Epoxy resin	proprietary data		1.125	mg
			Supplier	Phenolic Resin	Proprietary Data		0.375	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.125	mg
			Supplier	Carbon Black (C)	1333-86-4		0.075	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		12.3	mg
Plating	0.6	mg	Supplier	Tin (Sn)	7440-31-5		0.6	mg
Wire Bond - Cu	0.04	mg	Supplier	Copper (Cu)	7440-50-8		0.04	mg